

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	45	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	I _C	3	A
Peak Pulse Current	I _{CM}	6	A
Base Current	I _B	0.5	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

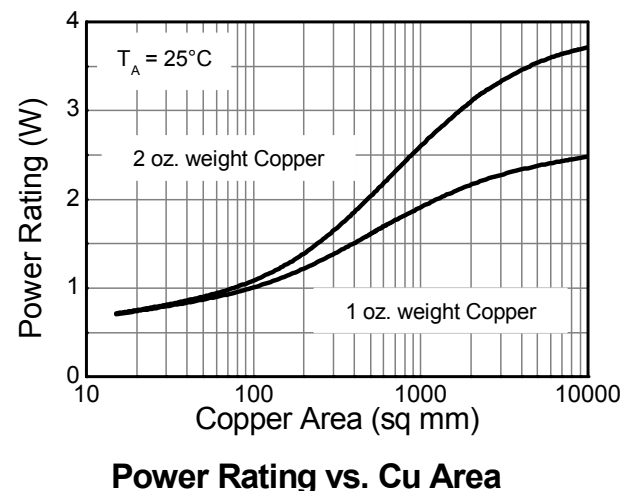
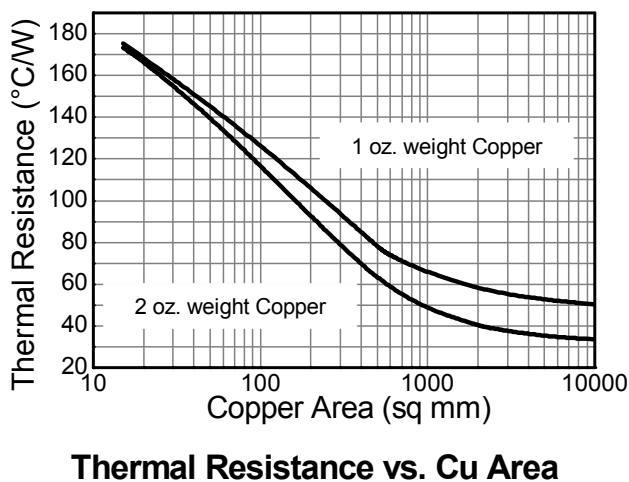
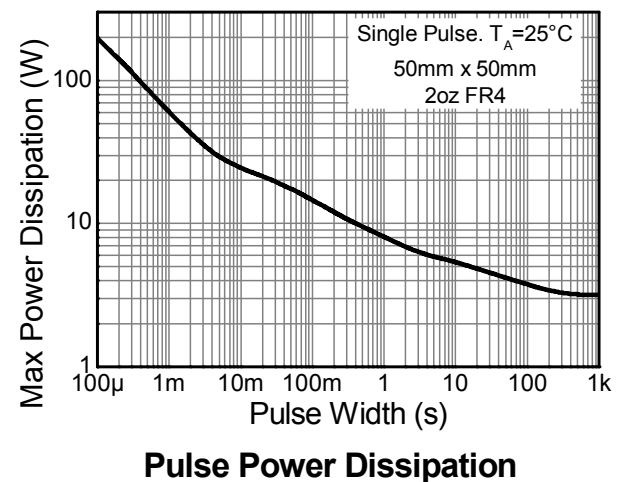
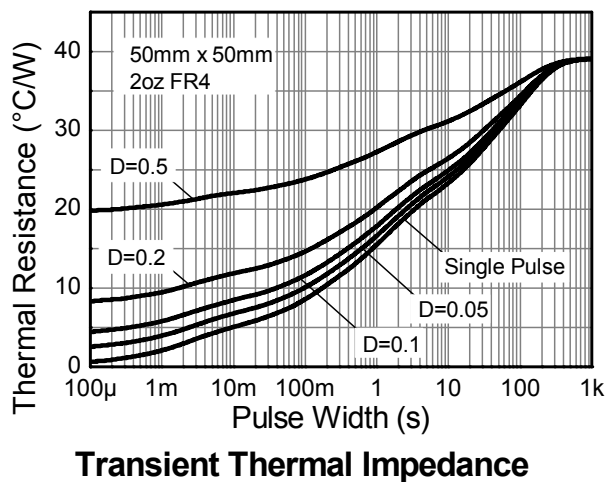
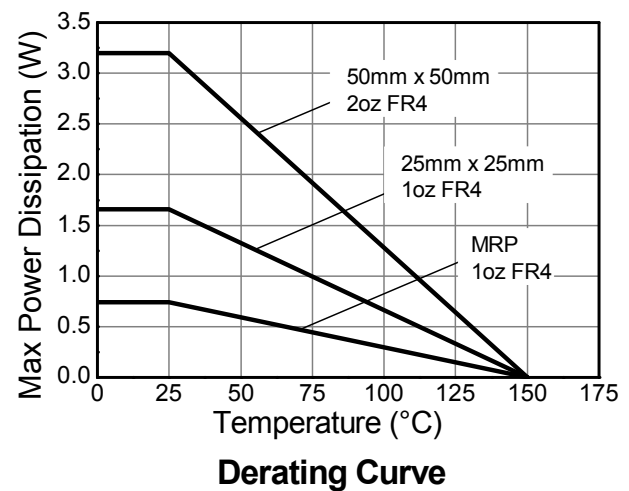
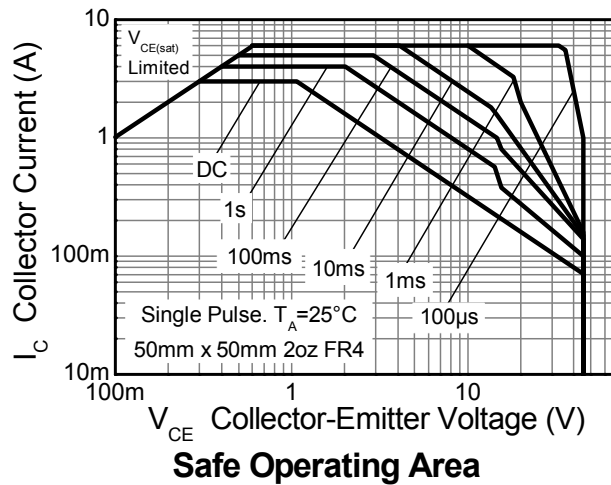
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	3.2	W
		1.7	
		0.74	
Thermal Resistance, Junction to Ambient Air	R _{θJA}	39	°C/W
		75	
		169	
Thermal Resistance, Junction to Leads	R _{θJL}	9	°C
Thermal Resistance, Junction to Case	R _{θJC}	10	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 11)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
- For a device mounted with the exposed collector pad on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 - Same as note (6), except mounted on 25mm x 25mm 1oz copper.
 - Same as note (6), except mounted on minimum recommended pad (MRP) layout.
 - Thermal resistance from junction to solder-point (on the exposed collector pad).
 - Thermal resistance from junction to the top of the case.
 - Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

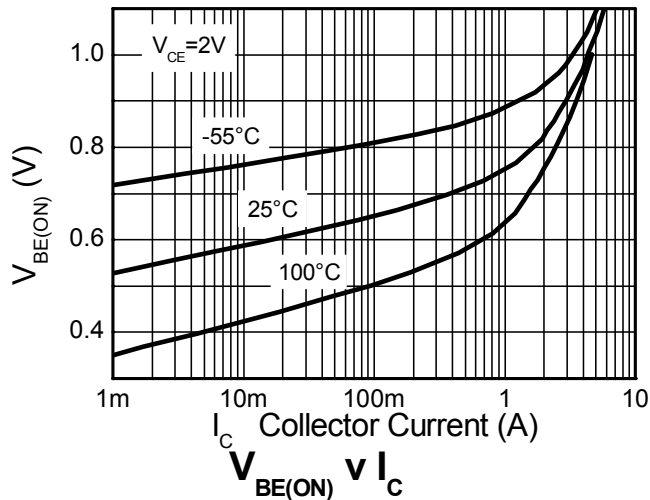
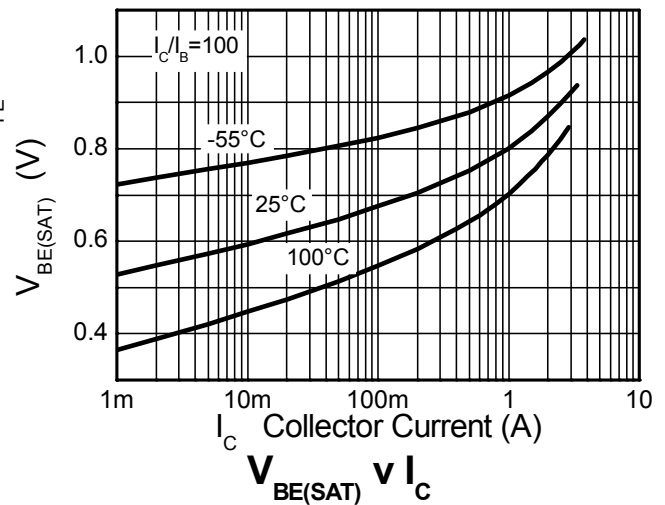
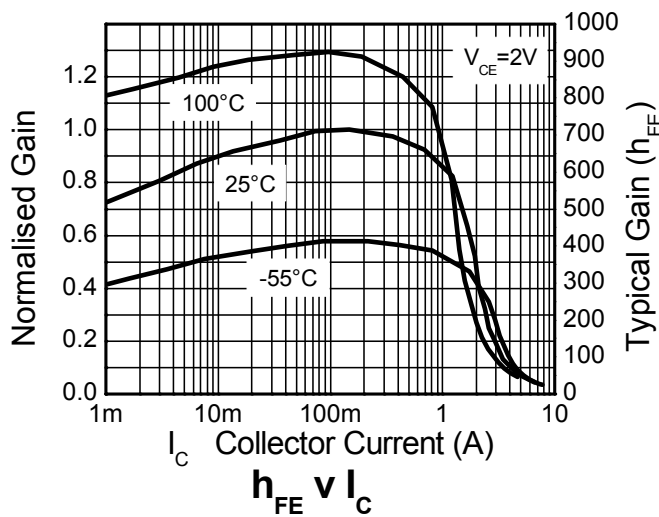
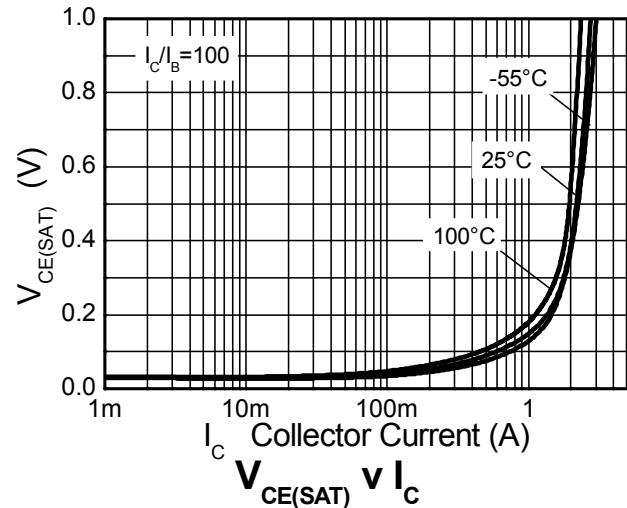
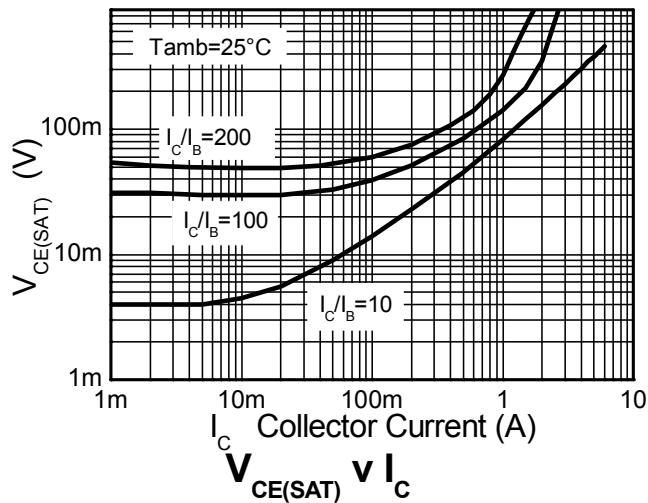


Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV _{CBO}	60	145	—	V	I _C = 100μA, I _E = 0
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	45	65	—	V	I _C = 10mA, I _B = 0
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.2	—	V	I _E = 100μA, I _C = 0
Collector-Base Cutoff Current	I _{CBO}	—	<1	20	nA	V _{CB} = 35V, I _E = 0
Collector-Emitter Cutoff Current	I _{CES}	—	<1	20	nA	V _{CB} = 35V, V _{BE} = 0
Emitter-Base Cutoff Current	I _{EBO}	—	<1	20	nA	V _{EB} = 5.6V, I _C = 0
ON CHARACTERISTICS (Note 12)						
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	50	85	mV	I _C = 100mA, I _B = 0.5mA
		—	240	360		I _C = 1A, I _B = 5mA
		—	210	320		I _C = 2A, I _B = 40mA
		—	230	350		I _C = 3A, I _B = 150mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	1.0	1.2	V	I _C = 3A, I _B = 150mA
Base-Emitter Turn-On Voltage	V _{BE(ON)}	—	0.9	1.1	V	I _C = 3A, V _{CE} = 2V
DC Current Gain	h _{FE}	500	700	—	—	I _C = 100mA, V _{CE} = 2V
		400	600	—		I _C = 1A, V _{CE} = 2V
		150	350	—		I _C = 2A, V _{CE} = 2V
		60	120	—		I _C = 3A, V _{CE} = 2V
AC CHARACTERISTICS						
Transition Frequency	f _T	150	—	—	MHz	I _C = 50mA, V _{CE} = 5V, f = 50MHz
Output Capacitance	C _{obo}	—	16	—	pF	V _{CB} = 10V, f = 1MHz
Switching Times	t _{on}	—	33	—	ns	V _{CC} = 10V, I _C = 500mA, I _{B1} = -I _{B2} = 50mA
	t _{off}	—	1300	—	ns	

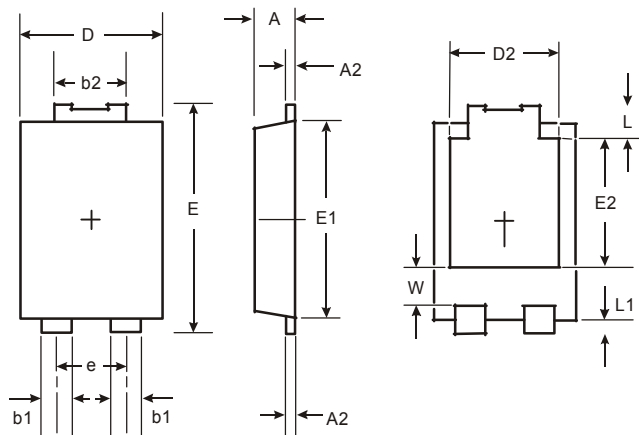
Note: 12. Pulse Test: Pulse width ≤300μs. Duty cycle ≤2.0%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

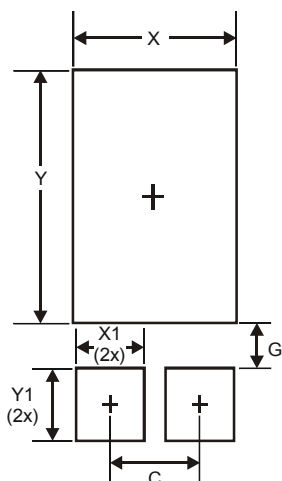
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

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